

● FBP1006-2A Power Dissipation

Power dissipation data for the FBP1006-2A is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board
Ambient: Natural convection
Soldering: Lead (Pb) free
Board: Dimensions 114.3mm×76.2mm
Copper (Cu) traces occupy 74.2mm of the board area
In back faces
Material: Glass Epoxy (FR-4)
Thickness: 1.6 mm

2. Power Dissipation vs. Ambient Temperature

Board Mount ($T_{jmax} = 125^{\circ}\text{C}$)

Ambient Temperature ($^{\circ}\text{C}$)	Power Dissipation P_d (mW)	Thermal Resistance ($^{\circ}\text{C}/\text{W}$)
25	110	909.09
85	44	

